

ABSTRACT

The present invention provides a resin composition containing (A) one or more selected from the group consisting of a maleimide resin having one or more N-substituted maleimide groups and a derivative of the maleimide resin, and (B) a compound having a vinyl benzyl group, in which the component (B) contains one or more selected from the group consisting of (B1) a compound having 3 or more vinyl benzyl groups bonded to an oxygen atom and (B2) a compound having one or more vinyl benzyl groups bonded to a carbon atom, and a prepreg, a laminate, a resin film, a printed wiring board, and a semiconductor package in which the resin composition is used.